

Prototyping circuit board for 0805, 1206, SOIC, SOT and other SMT parts.

## Features

- SMT rectangle pads are spaced for 0805 and 1206 components.
  - **SMTboard** has three SOIC-32 footprints each routed to 32 pads.
  - Solid ground plane on back side for low noise in RF and high speed logic circuits.
  - Every second SMT rectangle pad has an unplated hole for easy connection to the ground plane on the back side. Just insert a wire and solder.
  - Two power rails. Four mounting holes.
- Standard single height (3U) Eurocard/VME size.
  - Twelve SOT23 footprints. SOT223 and additional SOT23 parts can fit on the SMT rectangle pads.
  - SMT rectangle pads have 0.1" spacing to allow DIP ICs and headers to be attached.
  - Through hole prototyping area for headers, power connections, and DIP ICs.
  - The **BusBoard** zig-zag circuit pattern on the through hole area allows easy access to both sides of headers and DIP ICs.

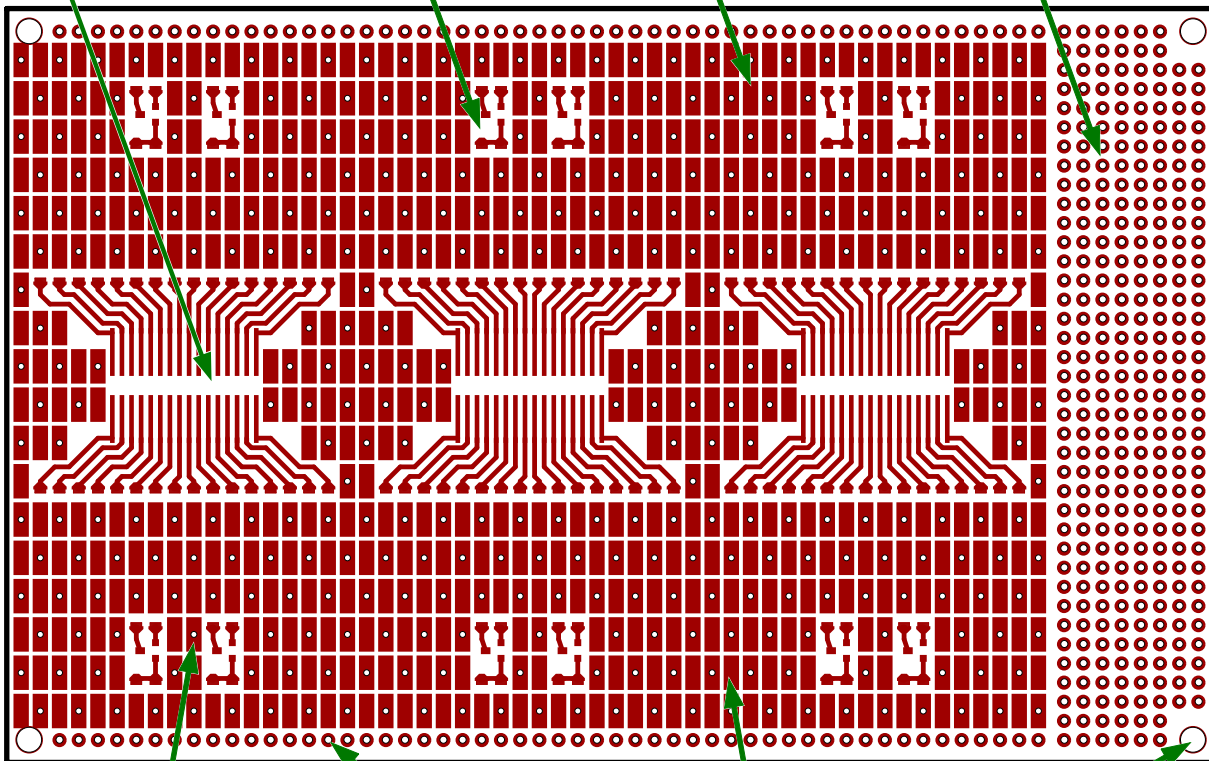
## Board Layout (component side)

SOIC-32 footprints routed to 32 pads.

SOT-23 footprints routed to four pads.

SMT pads are spaced for 0805 and 1206 SMT components.

Through-hole area for DIP ICs and headers.



Every second SMT pad has an unplated hole for easy connection to the ground plane. Just insert a wire and solder.

Two power rails.

SMT pads have 0.1" spacing. DIP ICs can be soldered to pads.

Four mounting holes.

## **SMTboard-3U** Data Sheet, Continued

### **Specifications**

- Etched FR4 glass-epoxy circuit board.
- 1oz/ft<sup>2</sup> copper, tinned for easy soldering.
- SMTboard-3U                    3.9" wide, 6.3" long, 1/16" thick (100 x 160 x 1.6mm).
- SMTboard-3U-THIN        3.9" wide, 6.3" long, 1/32" thick (100 x 160 x 0.8mm).
- Holes are drilled on 0.1" (2.54mm) centers in through hole area. All holes are unplated.
- 0.037" (0.94mm) holes (unplated) for ICs or square post headers in through hole area.
- 0.031" (0.79mm) holes (unplated) for connections to ground plane in SMT area.

**Order Part# SMT3U**  
**or SMT3UT (thin version)**

### **Board Layout (ground plane side)**

Solid ground plane for  
high-speed logic and RF circuits.

Zig-zag pattern allows easy access  
to both sides of DIP ICs and headers.

